

# 應用於軟板上具高深鍍能力的下世代電鍍藥水

## Next Generation High Throwing Power Solution on Flexible Board Electroplating Application



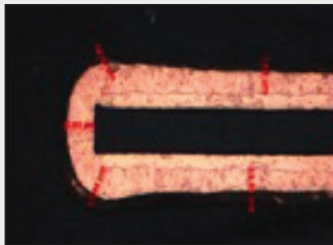
### COPPER GLEAM™ HV-303 Acid Copper

COPPER GLEAM™ HV-303 Acid Copper is specifically formulated for soluble anodes with direct current (DC) operation on flexible board. The product offers high throwing power and produces uniform, bright deposits of high ductility and tensile strength, at a reduced cost of operation.

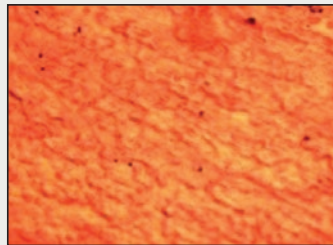
COPPER GLEAM™ HV-303 為一款應用在軟板生產上，搭配可溶性陽極以及直流電設備的酸性電鍍銅藥水。該產品展現優異的深鍍能力、表面光亮平整且具高度延展力等特性，低面銅優勢可使單位生產成本相對較低。

#### Advantage of COPPER GLEAM™ HV-303: COPPER GLEAM™ HV-303 具備以下優越的特性：

- Demonstrate higher than 150% throwing power on through-hole in most flexible material  
在多數軟板板材上可展現大於150%的通孔深度能力
- Bright, highly ductile, levelled deposits  
銅面光亮、有高度延展性且鍍面平整
- Wide Operation Current Density (10-30 ASF) with vertical type equipment  
可在較廣的操作電流密度下(10-30 ASF)，搭配垂直式設備作業
- DC process with soluble anodes for simple operation and elimination of idle time effects  
直流電搭配可溶性陽極的操作便於線上操作，即使設備停擺後重啟也影響不大
- 2 additives are both easily analyzed and controlled by conventional CVS  
兩劑型藥水的設計易於以傳統CVS方式進行分析控管



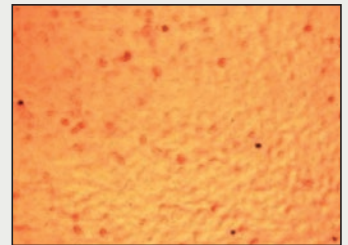
Rogers 0.330Z RA Copper Foil,  
PI Thickness: 1 mil  
Throwing Power= 174%  
Knee Throwing Power= 139%



100X Microscope



For SinYang 0.330Z ED Copper Foil, PI Thickness: 1 mil  
Throwing Power= 207%  
Knee Throwing Power= 147%



100X Microscope